SEALABLE SHEET AND ELECTRONIC ELEMENT DEVICE

ABSTRACT

[Document] Abstract

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[Problem]

To provide a sealable sheet and an electronic element device, both of which can suppress the percentage of the change in the adhesive force and reduce the unreacted material in the sealing body sheet that is a cured product.

[Means for Solving the Problem]

A sealable sheet contains an epoxy resin, a phenol resin, a urea-based curing accelerator, and an inorganic filler. The sealable sheet has an adhesive force A0 immediately after the sealable sheet is produced and an adhesive force A1 after the sealable sheet is left to stand at 23℃ and 50% for 24 hours. The percentage ([A0-A1]/A0×100) of the change (A0-A1) from the adhesive force A0 to the adhesive force A1 over the adhesive force A0 is 10% or less. The calorific value of the sealable sheet is obtained by differential scanning calorimetry immediately after the sealable sheet is produced and after the sealable sheet is heated at 150℃ for 20 minutes. The ratio of the calorific value after the heating to the calorific value immediately after the production is 0.10 or less.

[Selected drawing] Fig. 1